

SOT855-2

plastic thermal enhanced thin quad flat package; 64 leads; 10 x 10 x 1 mm; exposed diepad

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFP64
Package type industry code	HTQFP64
Package style descriptive code	HTQFP (thermal enhanced thin quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	- - -
Mounting method type	S (surface mount)
Issue date	15-2-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	1	-	1.09	1.2	mm
A ₂	package height	0.95	-	1	1.1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	64	-	



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2. Package outline

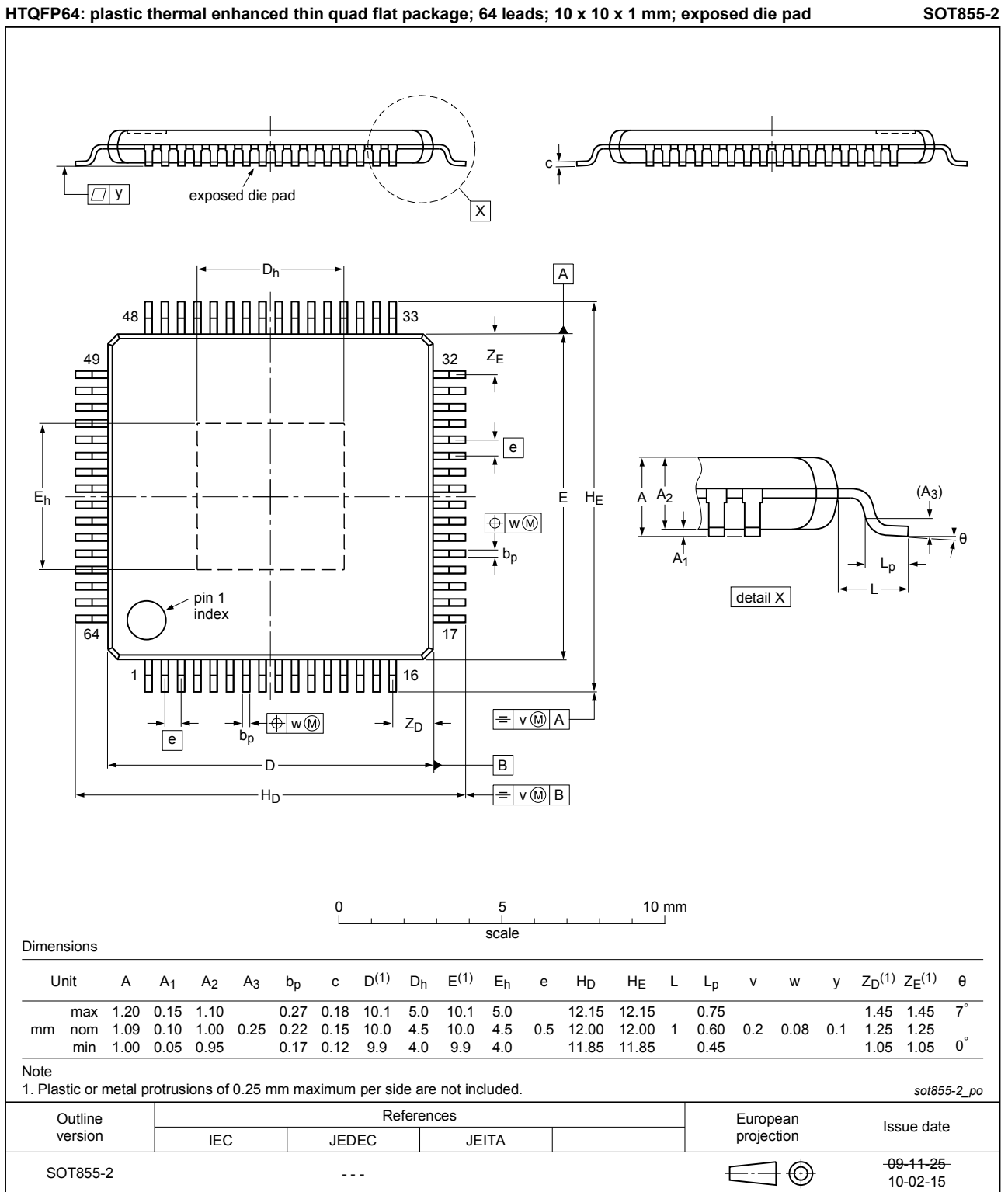


Fig. 1. Package outline HTQFP64 (SOT855-2)

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3. Legal information

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